



M T B F (E I A J R C R - 9 1 0 2 B)

Model	GT2.5-12
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No.	Parts		Q'ty of Device	Failure rate [10 ⁻⁶ /H]	Reference
1	IC	Linear	2	0.0480	
2	Transistors	NPN/PNP	0	0.0000	
3	Transistors	Power NPN/PNP	1	0.0420	
4	FET	MOS FET	1	0.0990	
5	Diodes	FR	2	0.0440	
6	Diodes	Zener	2	0.0480	
7	Diodes	bridge	2	0.1320	
8	Resistors	Metal Film	19	0.3040	
9	Resistors	Power Film	4	0.1640	
10	Resistors	variable	1	0.0160	
11	Capacitors	Aluminum Electrolytic	9	0.1710	
12	Capacitors	Film	5	0.0420	
13	Transformer	Power	1	0.3600	
14	Fuses		1	0.0200	
15	Connectors	Printed Crcuit Board	7	0.3640	
16	Connection	Hand Solder	18	0.0468	
17	Connection	Flow Solder	247	0.1284	
18	Connection	Crimp	38	0.0236	
19	Connection	Screw	8	0.0080	
20	Printed Crcuit Board	Through Hole	3	0.1350	
Total Failure Rate [10 ⁻⁶ /H]				2.1958	

M T B F	[H]	455,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-